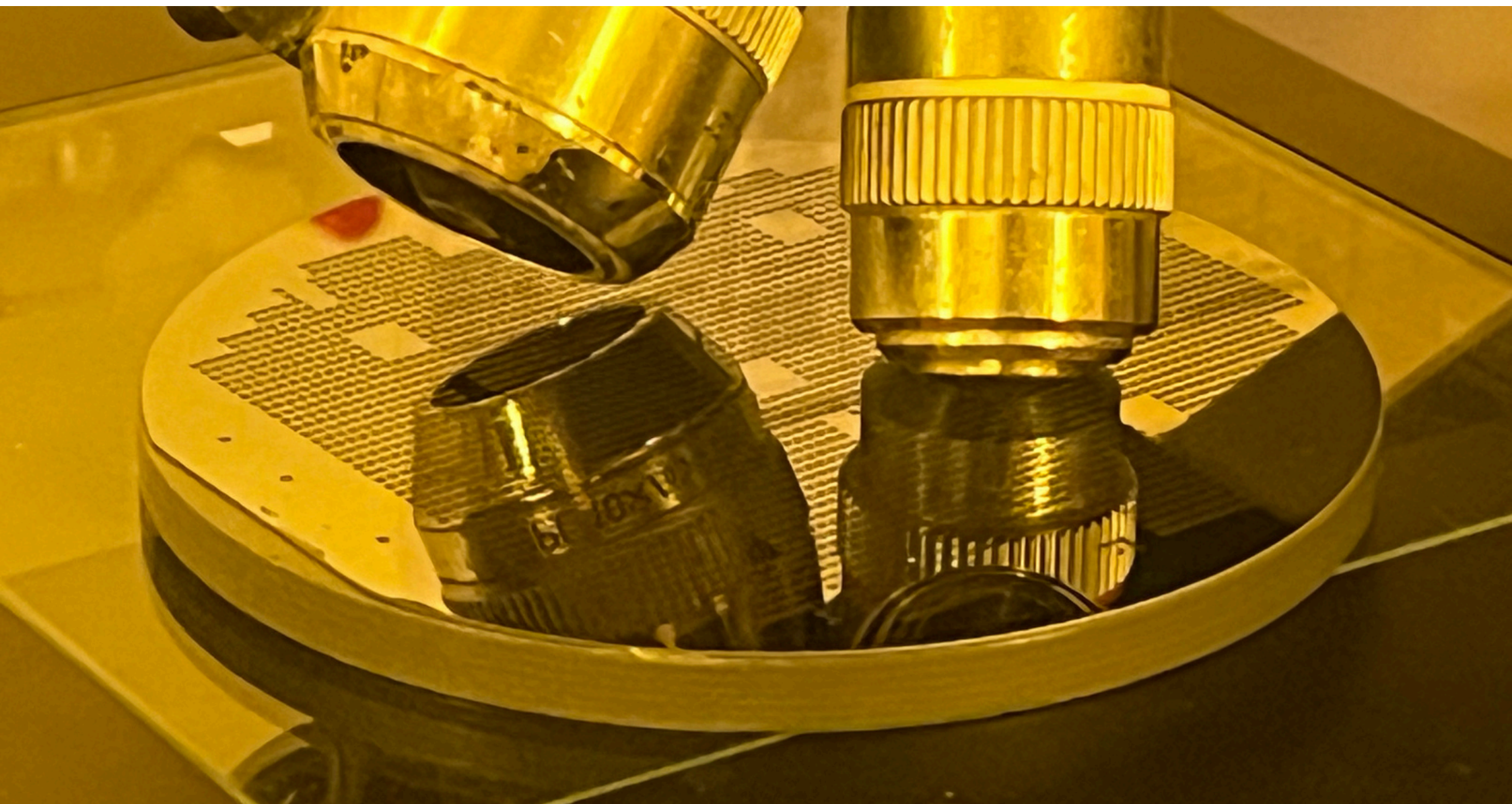




Packaging & Integration Engineer

From lab innovation to industrialization

Shape how tomorrow's micro-devices are
powered - from MedTech to Space



Apply at : contact@voltify-semiconductor.com



Integration & Packaging Engineer

Start date: March 2026



Company Context

Voltify is a deeptech start-up based in Villeneuve d’Ascq (Hauts-de-France), specializing in the design, manufacturing, and commercialization of energy

storage micro-devices, such as micro-capacitors and micro-batteries. Built on over 15 years of patented research at the IEMN laboratory, Voltify has developed breakthrough technology enabling the **extreme miniaturization of energy storage systems** while maintaining **exceptionally high energy density**.

Mission

Some devices can afford failure. Ours can’t.

Packaging is the frontier between lab breakthroughs and real-world impact.

Role Overview

As part of our industrial scale-up, you will develop **integration and packaging methods** for our components — critical steps in our product development and manufacturing process.

Responsibilities

Design & Integration

- **Design and optimize packaging architectures** to handle thermal, electrical, and mechanical constraints.
- **Develop advanced interconnection technologies (wire bonding, flip-chip, TSV (Through-Silicon Vias), back-side connections)** compatible with microelectronics standards.
- **Develop integration and assembly processes** for microelectronic components.
- **Select and qualify substrates, adhesives, encapsulants and other materials** to meet miniaturization, reliability and environmental resistance requirements.

Prototyping & Testing

- **Prototype and test devices** in cleanroom or lab environments, closely collaborating with fabrication teams.
- **Plan, execute, and analyze electrical, mechanical and thermal test campaigns** to validate designs and processes.

Scale-up

- **Identify production-related constraints and propose solutions** to ensure scalability, repeatability, and robustness of the processes.

Candidate Profile

Technical

- 3+ years of experience in microelectronics packaging (MedTech, aerospace, IoT or similar)
- Hand-on experience with bonding, encapsulation and interconnect technologies
- French and English (professional)

Soft Skills

- **Precision and structured working methods.**
- **Intellectual curiosity and adaptability.**
- **Strong interpersonal skills and collaborative mindset.**

To apply

Send your CV and a short introduction to: contact@voltify-semiconductor.com

Include “Packaging Engineer Application” in the subject line. We review applications as they come in.

Location:
Villeneuve d’Ascq,
France

Permanent position

#EnergyStorage

#MicroFabrication

#MicroElectronics

#AdvancedPackaging

#DeviceIntegration

Cleverness

Curiosity

Teamwork